



Attorney Docket No. 0756-7719

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

The Patent Application of:

Shunpei YAMAZAKI et al.

Serial No. 10/581,674

Filed: June 5, 2006

For: METHOD FOR MANUFACTURING
THIN FILM INTEGRATED CIRCUIT
DEVICE, NONCONTACT THIN FILM
INTEGRATED CIRCUIT DEVICE
AND METHOD FOR
MANUFACTURING THE SAME, AND
IDTAG AND COIN INCLUDING THE
NONCONTACT THIN FILM
INTEGRATED CIRCUIT

) Group Art Unit: 2823

) Examiner: William D. Coleman

) CERTIFICATE OF MAILING
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Commissioner for Patents, P.O. Box 1450,
Alexandria, VA 22313-1450, on July 7, 2008.

Adam M. Stamps

AMENDMENT

Honorable Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Official Action dated March 5, 2008, please consider the following amendments and remarks in connection with the above-identified application.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims, which begins on page 3 of this paper.

Remarks begin on page 12 of this paper.